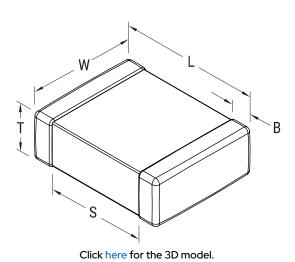




SMD Comm X8G HT150C Flex, Ceramic, 0.1 uF, 2%, 50 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 2220, 3.5 mm



General Information		
Series	SMD Comm X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	130 mg	
Shelf Life	78 Weeks	
MSL	1	

0.1 uF

1 kHz 1.0Vrms

10 GOhms

Dimensions	
Chip Size	2220
L	5.9mm +/-0.75mm
W	5mm +/-0.4mm
Т	1mm +/-0.15mm
S	3.5mm MIN
В	0.7mm +/-0.35mm

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W	5mm +/-0.4mm
Т	1mm +/-0.15mm
S	3.5mm MIN
В	0.7mm +/-0.35mm
Packaging Specifications	

W	5mm +/-0.4mm	Tolerance	2%
Т	1mm +/-0.15mm	Voltage DC	50 VDC
S	3.5mm MIN	Dielectric Withstanding Voltage	125 VDC
В	0.7mm +/-0.35mm	Temperature Range	-55/+150°C
		Temp. Coefficient	X8G
Packaging Specifications		Capacitance Change with	30 ppm/C, 1kHz 1.0Vrms
Packaging	T&R, 330mm, Plastic Tape	Reference to +25°C and 0 VDC Applied (TCC)	,, ,
Packaging Quantity	ing Quantity 4000	Dissipation Factor	0.1% 1 kHz 1.0Vrms
		Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
			Time is 1000 nours

Specifications

Measurement Condition

Insulation Resistance

Capacitance

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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